

SNx4LVC14A Hex Schmitt-Trigger Inverters

1 Features

- Operate From 1.65 V to 3.6 V V_{CC}
- Specified From -40°C to 85°C , -40°C to 125°C , and -55°C to 125°C
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 6.4 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at $V_{CC} = 3.3$ V, $T_A = 25^{\circ}\text{C}$
- I_{off} Support Live Insertion, Partial-Power-Down Mode and Back Drive protection
- On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

2 Applications

- Barcode Scanner
- Cable Solutions
- E-Books
- Embedded PCs
- Field Transmitter: Temperature or Pressure Sensors
- Fingerprint Biometrics
- HVAC: Heating, Ventilating, and Air Conditioning
- Network-Attached Storage (NAS)
- Server Motherboard and PSU
- Software Defined Radio (SDR)
- TV: High Definition (HDTV), LCD, and Digital
- Video Communications Systems
- Wireless Data Access Cards, Headsets, Keyboards, Mice, and LAN Cards

3 Description

The SN54LVC14A hex Schmitt-trigger inverter is designed for 2.7-V to 3.6-V V_{CC} operation, and the SN74LVC14A hex Schmitt-trigger inverter is designed for 1.65-V to 3.6-V V_{CC} operation.

The devices contain six independent inverters and perform the Boolean function $Y = \bar{A}$.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V or 5-V system environment.

Device Information(1)

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|------------|--------------------|
| SN54LVC14A | LCCC (20) | 8.90 mm x 8.90 mm |
| | CDIP (14) | 20.00 mm x 7.00 mm |
| | CFP (14) | 9.21 mm x 6.30 mm |
| SN74LVC14A | SO (14) | 10.20 mm x 5.30 mm |
| | SOIC (14) | 8.65 mm x 6.00 mm |
| | SSOP (14) | 6.20 mm x 5.30 mm |
| | TSSOP (14) | 5.00 mm x 4.40 mm |
| | TVSOP (14) | 4.40 mm x 3.60 mm |
| | VQFN (14) | 3.50 mm x 3.50 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Logic Diagram (Positive Logic)

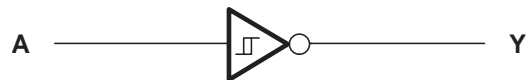


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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision Z (January 2014) to Revision AA

Page

| | |
|---|---|
| • Added <i>Applications</i> , <i>Device Information</i> table, <i>Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section | 1 |
| • Moved T_{stg} to <i>Absolute Maximum Ratings</i> table | 5 |

Changes from Revision Y (October 2010) to Revision Z

Page

| | |
|---|---|
| • Updated document to new TI data sheet format | 1 |
| • Updated <i>Features</i> | 1 |
| • Added Military Disclaimer to <i>Features</i> list | 1 |

5 Device Options

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|----------------|------------|--------------------|
| SN54LVC14AFK | LCCC (20) | 8.90 mm × 8.90 mm |
| SN54LVC14AJ | CDIP (14) | 20.00 mm × 7.00 mm |
| SN54LVC14AW | CFP (14) | 9.21 mm × 6.30 mm |
| SN74LVC14ANSR | SO (14) | 10.20 mm × 5.30 mm |
| SN74LVC14ADR | SOIC (14) | 8.65 mm × 6.00 mm |
| SN74LVC14ADT | | |
| SN74LVC14ADBR | SSOP (14) | 6.20 mm × 5.30 mm |
| SN74LVC14APWR | TSSOP (14) | 5.00 mm × 4.40 mm |
| SN74LVC14APWT | | |
| SN74LVC14ADGVR | TVSOP (14) | 4.40 mm × 3.60 mm |
| SN74LVC14ARGYR | VQFN (14) | 3.50 mm × 3.50 mm |

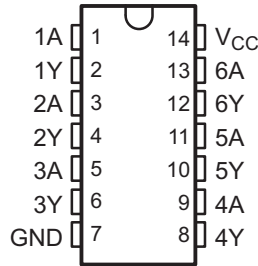
SN54LVC14A, SN74LVC14A

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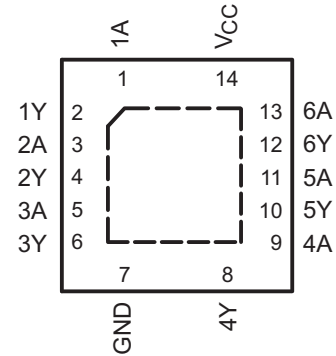
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6 Pin Configuration and Functions

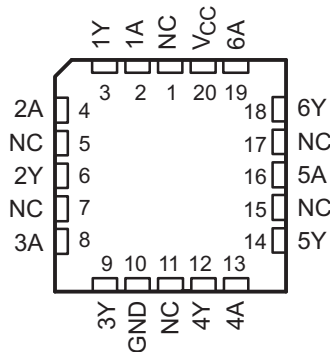
D, DB, DGV, NS, J, W, or PW Package
14-Pin SOIC, TVSOP, SSOP, SOP, CDIP, or TSSOP
Top View



RGY Package
14-Pin VQFN
Top View



FK Package
20-Pin LCCC
Top View



Pin Functions

| NAME | PIN | | I/O | DESCRIPTION |
|-----------------|---|------|-----|-------------|
| | SOIC, TVSOP, SSOP, SOP, CDIP, TSSOP, VQFN | LCCC | | |
| 1A | 1 | 2 | I | Data Input |
| 2A | 3 | 4 | I | Data Input |
| 3A | 5 | 8 | I | Data Input |
| 4A | 9 | 13 | I | Data Input |
| 5A | 11 | 16 | I | Data Input |
| 6A | 13 | 19 | I | Data Input |
| GND | 7 | 10 | — | Ground |
| V _{CC} | 14 | 20 | — | Power |
| 1Y | 2 | 3 | O | Data Output |
| 2Y | 4 | 6 | O | Data Output |
| 3Y | 6 | 9 | O | Data Output |
| 4Y | 8 | 12 | O | Data Output |
| 5Y | 10 | 14 | O | Data Output |
| 6Y | 12 | 18 | O | Data Output |

Pin Functions (continued)

| NAME | PIN | | I/O | DESCRIPTION |
|------|--|------|-----|-------------|
| | SOIC, TVSOP, SSOP, SOP, CDIP, TSSOP, VQFN | LCCC | | |
| NC | — | 1 | — | No Connect |
| | | 5 | | |
| | | 7 | | |
| | | 11 | | |
| | | 15 | | |
| | | 17 | | |

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT | |
|-----------|--|--|----------------|------|----|
| V_{CC} | Supply voltage | -0.5 | 6.5 | V | |
| V_I | Input voltage ⁽²⁾ | -0.5 | 6.5 | V | |
| V_O | Output voltage ⁽²⁾⁽³⁾ | -0.5 | $V_{CC} + 0.5$ | V | |
| I_{IK} | Input clamp current | $V_I < 0$ | -50 | mA | |
| I_{OK} | Output clamp current | $V_O < 0$ | -50 | mA | |
| I_O | Continuous output current | | ±50 | mA | |
| | Continuous current through V_{CC} or GND | | ±100 | mA | |
| P_{tot} | Power dissipation | $T_A = -40^\circ\text{C}$ to 125°C ⁽⁴⁾⁽⁵⁾ | 500 | mW | |
| T_{stg} | Storage temperature | | -65 | 150 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the *Recommended Operating Conditions* table.
- (4) For the D package: above 70°C , the value of P_{tot} derates linearly with 8 mW/K.
- (5) For the DB, DGV, NS, and PW packages: above 60°C , the value of P_{tot} derates linearly with 5.5 mW/K.

7.2 ESD Ratings

| | | VALUE | UNIT |
|-------------|-------------------------|--|-------|
| $V_{(ESD)}$ | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾ | +2000 |
| | | Charged-device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾ | +1000 |
| | | Machine Model | 200 |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions, SN54LVC14A⁽¹⁾

| | | SN54LVC14A | | UNIT | |
|----------|----------------|---------------------|----------|------|---|
| | | -55 TO 125°C | | | |
| | | MIN | MAX | | |
| V_{CC} | Supply voltage | Operating | 2 | 3.6 | V |
| | | Data retention only | 1.5 | | |
| V_I | Input voltage | 0 | 5.5 | V | |
| V_O | Output voltage | 0 | V_{CC} | V | |

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

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Recommended Operating Conditions, SN54LVC14A⁽¹⁾ (continued)

| | | | | SN54LVC14A | | UNIT |
|-----------------|---------------------------|-------------------------|--|--------------|-----|------|
| | | | | –55 TO 125°C | | |
| | | | | MIN | MAX | |
| I _{OH} | High-level output current | V _{CC} = 2.7 V | | –12 | | mA |
| | | V _{CC} = 3 V | | –24 | | |
| I _{OL} | Low-level output current | V _{CC} = 2.7 V | | 12 | | mA |
| | | V _{CC} = 3 V | | 24 | | |

7.4 Recommended Operating Conditions, SN74LVC14A⁽¹⁾

| | | | | SN74LVC14A | | | | UNIT | | |
|-----------------|---------------------------|--------------------------|-----------------|-----------------------|-----------------|-------------|-----------------|------|-----------------|-----|
| | | | | T _A = 25°C | | –40 TO 85°C | | | –40 TO 125°C | |
| | | | | MIN | MAX | MIN | MAX | | MIN | MAX |
| V _{CC} | Supply voltage | Operating | | 1.65 | 3.6 | 1.65 | 3.6 | 1.65 | 3.6 | V |
| | | Data retention only | | 1.5 | | 1.5 | | 1.5 | | |
| V _I | Input voltage | 0 | 5.5 | 0 | 5.5 | 0 | 5.5 | 0 | 5.5 | V |
| V _O | Output voltage | 0 | V _{CC} | 0 | V _{CC} | 0 | V _{CC} | 0 | V _{CC} | V |
| I _{OH} | High-level output current | V _{CC} = 1.65 V | | –4 | | –4 | | –4 | | mA |
| | | V _{CC} = 2.3 V | | –8 | | –8 | | –8 | | |
| | | V _{CC} = 2.7 V | | –12 | | –12 | | –12 | | |
| | | V _{CC} = 3 V | | –24 | | –24 | | –24 | | |
| I _{OL} | Low-level output current | V _{CC} = 1.65 V | | 4 | | 4 | | 4 | | mA |
| | | V _{CC} = 2.3 V | | 8 | | 8 | | 8 | | |
| | | V _{CC} = 2.7 V | | 12 | | 12 | | 12 | | |
| | | V _{CC} = 3 V | | 24 | | 24 | | 24 | | |

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

7.5 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | SNx4LVC257A | | | | | UNIT | |
|-------------------------------|--|-------------|-----------|-------------|---------|------------|------|------------|
| | | D (SOIC) | DB (SSOP) | DGV (TVSOP) | NS (SO) | PW (TSSOP) | | RGY (LCCC) |
| | | 14 PINS | | | | 20 PINS | | |
| R _{θJA} | Junction-to-ambient thermal resistance | 86 | 96 | 127 | 76 | 113 | 47 | °C/W |

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

7.6 Electrical Characteristics, SN54LVC14A

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | V _{CC} | | SN54LVC14A | | | UNIT |
|-----------------|--------------------------|-----------------|--|-----------------|--|--------------|-----|-----|------|
| | | | | | | –55 TO 125°C | | | |
| | | | | | | MIN | TYP | MAX | |
| V _{T+} | Positive-going threshold | | | 2.7 V | | 0.8 | | 2 | V |
| | | | | 3 V | | 0.9 | | 2 | |
| | | | | 3.6 V | | 1.1 | | 2 | |
| V _{T–} | Negative-going threshold | | | 2.7 V | | 0.4 | | 1.4 | V |
| | | | | 3 V | | 0.6 | | 1.5 | |
| | | | | 3.6 V | | 0.8 | | 1.7 | |

Electrical Characteristics, SN54LVC14A (continued)

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | SN54LVC14A | | | UNIT |
|---|---|-----------------|-----------------------|------------------|---------|---------|
| | | | –55 TO 125°C | | | |
| | | | MIN | TYP | MAX | |
| ΔV_T Hysteresis ($V_{T+} - V_{T-}$) | | 2.7 V | 0.3 | | 1.1 | V |
| | | 3 V | 0.3 | | 1.2 | |
| | | 3.6 V | 0.3 | | 1.2 | |
| V _{OH} | I _{OH} = –100 μ A | 2.7 V to 3.6 V | V _{CC} – 0.2 | | | V |
| | V _{OL} | 2.7 V | 2.2 | | | |
| | I _I | | 2.4 | | | |
| ΔI_{CC} | I _{OL} = 100 μ A | 2.7 V to 3.6 V | | | 0.2 | V |
| | C _i | 2.7 V | | | 0.4 | |
| | I _{OL} = 24 mA | 3 V | | | 0.55 | |
| | V _I = 5.5 V or GND | 3.6 V | | | ± 5 | μ A |
| | V _I = V _{CC} or GND, I _O = 0 | 3.6 V | | | 10 | μ A |
| | One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND | 2.7 V to 3.6 V | | | 500 | μ A |
| | V _I = V _{CC} or GND | 3.3 V | | 5 ⁽¹⁾ | | pF |

(1) T_A = 25°C

7.7 Electrical Characteristics, SN74LVC14A

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | SN74LVC14A | | | | | | UNIT | |
|---|-----------------|-----------------|-----------------------|-----|------|-------------|------|--------------|------|-----|
| | | | T _A = 25°C | | | –40 TO 85°C | | –40 TO 125°C | | |
| | | | MIN | TYP | MAX | MIN | MAX | MIN | | MAX |
| V _{T+} Positive-going threshold | | 1.65 V | 0.4 | | 1.3 | 0.4 | 1.3 | 0.4 | 1.3 | V |
| | | 1.95 V | 0.6 | | 1.5 | 0.6 | 1.5 | 0.6 | 1.5 | |
| | | 2.3 V | 0.8 | | 1.7 | 0.8 | 1.7 | 0.8 | 1.7 | |
| | | 2.5 V | 0.8 | | 1.7 | 0.8 | 1.7 | 0.8 | 1.7 | |
| | | 2.7 V | 0.8 | | 2 | 0.8 | 2 | 0.8 | 2 | |
| | | 3 V | 0.9 | | 2 | 0.9 | 2 | 0.9 | 2 | |
| | | 3.6 V | 1.1 | | 2 | 1.1 | 2 | 1.1 | 2 | |
| V _{T–} Negative-going threshold | | 1.65 V | 0.15 | | 0.85 | 0.15 | 0.85 | 0.15 | 0.85 | V |
| | | 1.95 V | 0.25 | | 0.95 | 0.25 | 0.95 | 0.25 | 0.95 | |
| | | 2.3 V | 0.4 | | 1.2 | 0.4 | 1.2 | 0.4 | 1.2 | |
| | | 2.5 V | 0.4 | | 1.2 | 0.4 | 1.2 | 0.4 | 1.2 | |
| | | 2.7 V | 0.4 | | 1.4 | 0.4 | 1.4 | 0.4 | 1.4 | |
| | | 3 V | 0.6 | | 1.5 | 0.6 | 1.5 | 0.6 | 1.5 | |
| | | 3.6 V | 0.8 | | 1.7 | 0.8 | 1.7 | 0.8 | 1.7 | |
| ΔV_T Hysteresis ($V_{T+} - V_{T-}$) | | 1.65 V | 0.1 | | 1.15 | 0.1 | 1.15 | 0.1 | 1.15 | V |
| | | 1.95 V | 0.15 | | 1.25 | 0.15 | 1.25 | 0.15 | 1.25 | |
| | | 2.3 V | 0.25 | | 1.3 | 0.25 | 1.3 | 0.25 | 1.3 | |
| | | 2.5 V | 0.25 | | 1.3 | 0.25 | 1.3 | 0.25 | 1.3 | |
| | | 2.7 V | 0.3 | | 1.1 | 0.3 | 1.1 | 0.3 | 1.1 | |
| | | 3 V | 0.3 | | 1.2 | 0.3 | 1.2 | 0.3 | 1.2 | |
| | | 3.6 V | 0.3 | | 1.2 | 0.3 | 1.2 | 0.3 | 1.2 | |

Electrical Characteristics, SN74LVC14A (continued)

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | SN74LVC14A | | | | | | UNIT | |
|--------------------------|--|-----------------|-----------------------|-----|-----|-----------------------|-----|-----------------------|------|-----|
| | | | T _A = 25°C | | | –40 TO 85°C | | –40 TO 125°C | | |
| | | | MIN | TYP | MAX | MIN | MAX | MIN | | MAX |
| V _{OH} | I _{OH} = –100 μA | 1.65 V to 3.6 V | V _{CC} – 0.2 | | | V _{CC} – 0.2 | | V _{CC} – 0.3 | | V |
| | I _{OH} = –4 mA | 1.65 V | 1.29 | | | 1.2 | | 1.05 | | |
| | I _{OH} = –8 mA | 2.3 V | 1.9 | | | 1.7 | | 1.65 | | |
| | I _{OH} = –12 mA | 2.7 V | 2.2 | | | 2.2 | | 2.05 | | |
| | | 3 V | 2.4 | | | 2.4 | | 2.25 | | |
| I _{OH} = –24 mA | 3 V | 2.3 | | | 2.2 | | 2 | | | |
| V _{OL} | I _{OL} = 100 μA | 1.65 V to 3.6 V | 0.1 | | | 0.2 | | 0.3 | | V |
| | I _{OL} = 4 mA | 1.65 V | 0.24 | | | 0.45 | | 0.6 | | |
| | I _{OL} = 8 mA | 2.3 V | 0.3 | | | 0.7 | | 0.75 | | |
| | I _{OL} = 12 mA | 2.7 V | 0.4 | | | 0.4 | | 0.6 | | |
| | I _{OL} = 24 mA | 3 V | 0.55 | | | 0.55 | | 0.8 | | |
| I _I | V _I = 5.5 V or GND | 3.6 V | ±1 | | | ±5 | | ±20 | | μA |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 3.6 V | 1 | | | 10 | | 40 | | μA |
| ΔI _{CC} | One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND | 2.7 V to 3.6 V | 500 | | | 500 | | 5000 | | μA |
| C _i | V _I = V _{CC} or GND | 3.3 V | 5 | | | | | | | pF |

7.8 Switching Characteristics, SN54LVC14A

 over operating free-air temperature range (unless otherwise noted) (see [Figure 2](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} | SN54LVC14A | | UNIT |
|-----------------|--------------|-------------|-----------------|--------------|-----|------|
| | | | | –55 TO 125°C | | |
| | | | | MIN | MAX | |
| t _{pd} | A | Y | 2.7 V | 7.5 | | ns |
| | | | 3.3 V ± 0.3 V | 1 | 6.4 | |

7.9 Switching Characteristics, SN74LVC14A

 over operating free-air temperature range (unless otherwise noted) (see [Figure 2](#))

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} | SN74LVC14A | | | | | | UNIT | |
|--------------------|--------------|-------------|-----------------|-----------------------|-----|------|-------------|-----|--------------|------|-----|
| | | | | T _A = 25°C | | | –40 TO 85°C | | –40 TO 125°C | | |
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | | MAX |
| t _{pd} | A | Y | 1.8 V ± 0.15 V | 1 | 5 | 10.5 | 1 | 11 | 1 | 13 | ns |
| | | | 2.5 V ± 0.2 V | 1 | 3.4 | 7.3 | 1 | 7.8 | 1 | 10 | |
| | | | 2.7 V | 1 | 3.6 | 7.3 | 1 | 7.5 | 1 | 9.5 | |
| | | | 3.3 V ± 0.3 V | 1 | 3.2 | 6.2 | 1 | 6.4 | 1 | 8 | |
| t _{sk(o)} | | | 3.3 V ± 0.3 V | 1 | | | 1 | | 1.5 | | ns |

7.10 Operating Characteristics

T_A = 25°C

| PARAMETER | TEST CONDITIONS | V _{CC} = 1.8 V | V _{CC} = 2.5 V | V _{CC} = 3.3 V | UNIT |
|---|-----------------|-------------------------|-------------------------|-------------------------|------|
| | | TYP | TYP | TYP | |
| C _{pd} Power dissipation capacitance | f = 10 MHz | 11 | 12 | 15 | pF |

7.11 Typical Characteristics

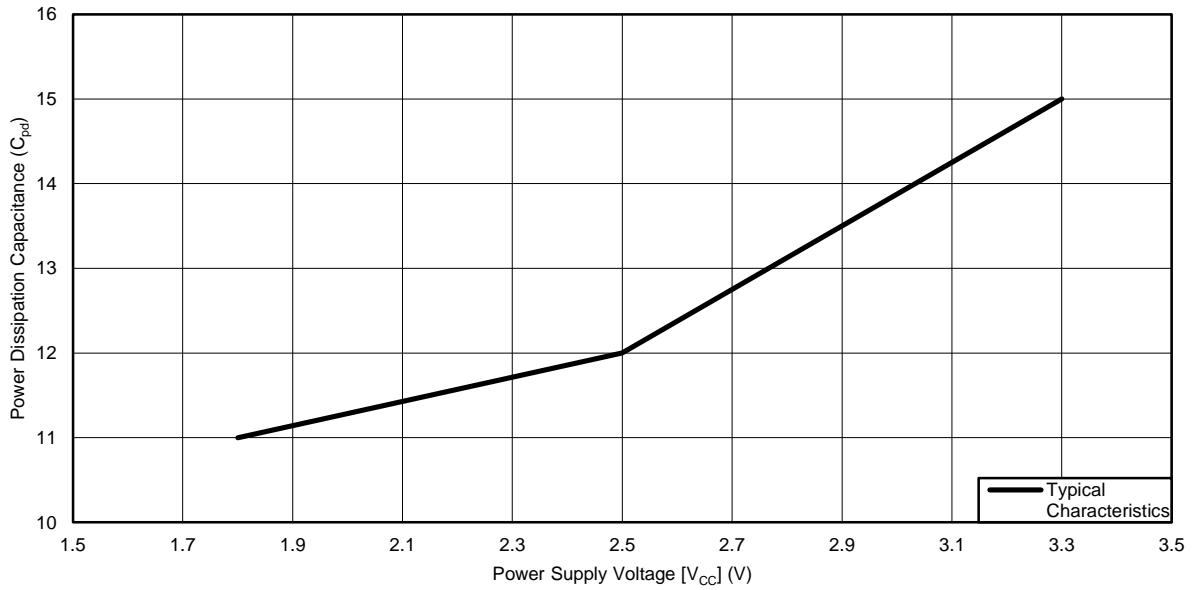
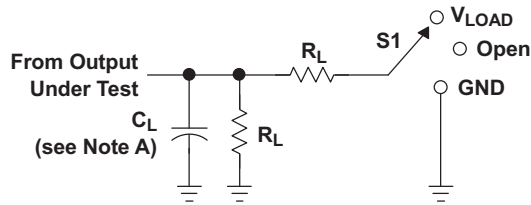


Figure 1. Power Dissipation Capacitance vs. Power Supply Voltage

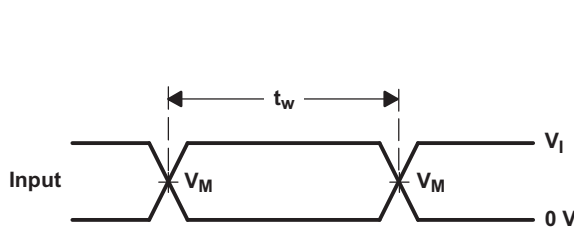
8 Parameter Measurement Information



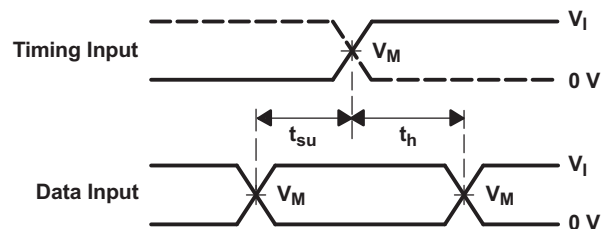
LOAD CIRCUIT

| TEST | S1 |
|-------------------|------------|
| t_{PLH}/t_{PHL} | Open |
| t_{PLZ}/t_{PZL} | V_{LOAD} |
| t_{PHZ}/t_{PZH} | GND |

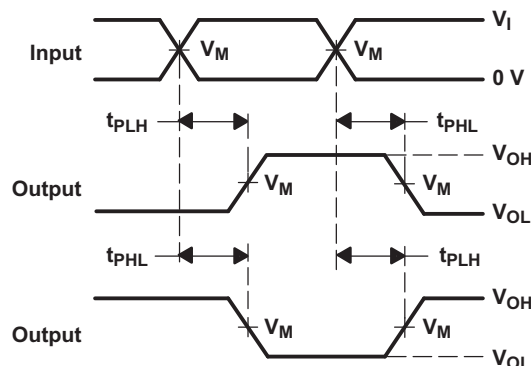
| V_{CC} | INPUTS | | V_M | V_{LOAD} | C_L | R_L | V_D |
|----------------------------------|----------|----------------------|------------|-------------------|-------|-------|--------|
| | V_I | t_r/t_f | | | | | |
| $1.8\text{ V} \pm 0.15\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 kW | 0.15 V |
| $2.5\text{ V} \pm 0.2\text{ V}$ | V_{CC} | $\leq 2\text{ ns}$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 W | 0.15 V |
| 2.7 V | 2.7 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 50 pF | 500 W | 0.3 V |
| $3.3\text{ V} \pm 0.3\text{ V}$ | 2.7 V | $\leq 2.5\text{ ns}$ | 1.5 V | 6 V | 50 pF | 500 W | 0.3 V |



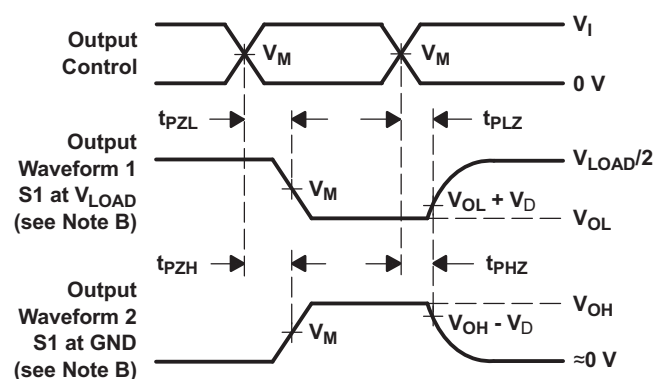
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq 10\text{ MHz}$, $Z_0 = 50\text{ }\Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

9 Detailed Description

9.1 Overview

The SN54LVC14A hex Schmitt-trigger inverter is designed for 2.7-V to 3.6-V V_{CC} operation, and the SN74LVC14A hex Schmitt-trigger inverter is designed for 1.65-V to 3.6-V V_{CC} operation.

The devices contain six independent inverters and perform the Boolean function $Y = \bar{A}$.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V or 5-V system environment.

9.2 Functional Block Diagram



Figure 3. Logic Diagram, Each Inverter (Positive Logic)

9.3 Feature Description

The SN54LVC14A hex Schmitt-trigger inverter is designed for 2.7-V to 3.6-V V_{CC} operation, and the SN74LVC14A hex Schmitt-trigger inverter is designed for 1.65-V to 3.6-V V_{CC} operation.

The devices contain six independent inverters and perform the Boolean function $Y = \bar{A}$.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V or 5-V system environment.

9.4 Device Functional Modes

Table 1 lists the functional modes for the SN54LVC14A and SN74LVC14A devices.

Table 1. Function Table (Each Inverter)

| INPUT A | OUTPUT Y |
|------------|-------------|
| H | L |
| L | H |

10 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

Physically interactive interface elements like push buttons or rotary knobs offer simple and easy ways to interact with an electronic system. Many of these physical interface elements often have issues with bouncing, or where the physical conductive contact can connect and disconnect multiple times during a button push or release. This bouncing can cause one or more faulty transient signals to be passed during this transitional period. These faulty signals can be observed in many common applications: for example, a television remote with bouncing error can adjust the TV channel multiple times despite the button being pushed only once. In order to mitigate these faulty signals, we can use a Schmitt-trigger, or a device with hysteresis, to remove these faulty signals. Hysteresis allows a device to "remember" its history, and in this case, the LVC14A uses this memory to debounce the physical element's signal, or filter the faulty transient signals and pass only the valid signal each time the element is used. In this example, we show a push button signal passed through an LVC14A that is debounced and inverted to the MCU for push detection.

10.2 Typical Application

The signal effects of the debounce circuit can be seen when comparing [Figure 5](#) and [Figure 6](#). In [Figure 5](#), the input is a very poor quality signal due to the error in the physical push button. If the MCU attempts to sample this input to detect a push, there is high probability that multiple push events will be falsely detected. Once the debounce circuit has been implemented, the input is cleaned up, and the MCU can perform push detection without any error, as seen in [Figure 6](#).

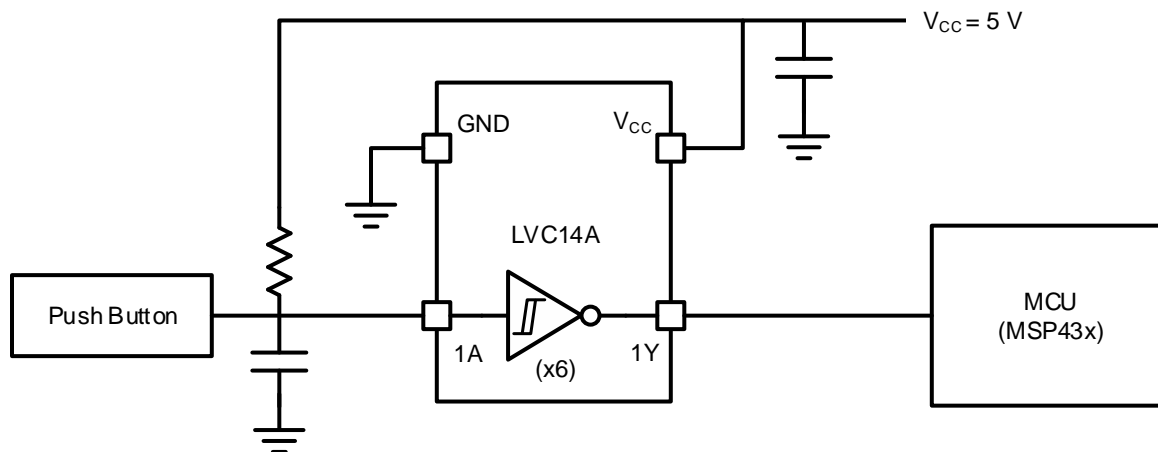


Figure 4. Debouncer Application Diagram

10.2.1 Design Requirements

The SN74LVC14A device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits.

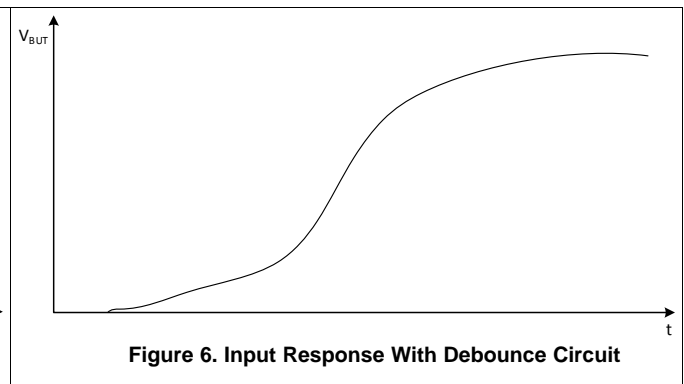
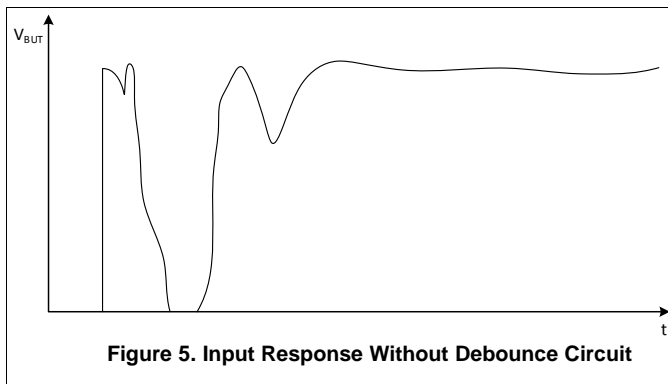
The SN74LVC14A allows for performing logical Boolean functions with hysteresis using digital signals. All input signals should remain as close as possible to either 0 V or V_{CC} for optimal operation.

Typical Application (continued)

10.2.2 Detailed Design Procedure

1. Recommended input conditions:
 - For rise time and fall time specifications, see $\Delta t/\Delta v$ in the table.
 - For specified high and low levels, see V_{IH} and V_{IL} in the table.
 - Inputs and outputs are overvoltage tolerant and can therefore go as high as 3.6 V at any valid V_{CC} .
2. Recommended output conditions:
 - Load currents should not exceed ± 50 mA.
3. Frequency selection criterion:
 - Added trace resistance and capacitance can reduce maximum frequency capability; follow the layout practices listed in the section.

10.2.3 Application Curves



11 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating listed in the table.

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1- μF bypass capacitor is recommended. If multiple pins are labeled V_{CC} , then a 0.01- μF or 0.022- μF capacitor is recommended for each V_{CC} because the V_{CC} pins are tied together internally. For devices with dual supply pins operating at different voltages, for example V_{CC} and V_{DD} , a 0.1- μF bypass capacitor is recommended for each supply pin. To reject different frequencies of noise, use multiple bypass capacitors in parallel. Capacitors with values of 0.1 μF and 1 μF are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

12 Layout

12.1 Layout Guidelines

When using multiple-bit logic devices, inputs must never float.

In many cases, functions (or parts of functions) of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or when only 3 of the 4 buffer gates are used. Such input pins must not be left unconnected, because the undefined voltages at the outside connections result in undefined operational states. [Figure 7](#) specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally they are tied to GND or V_{CC} , whichever makes more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver. If the transceiver has an output enable pin, it disables the output section of the part when asserted, which does not disable the input section of the I/Os. Therefore, the I/Os cannot float when disabled.

12.2 Layout Examples

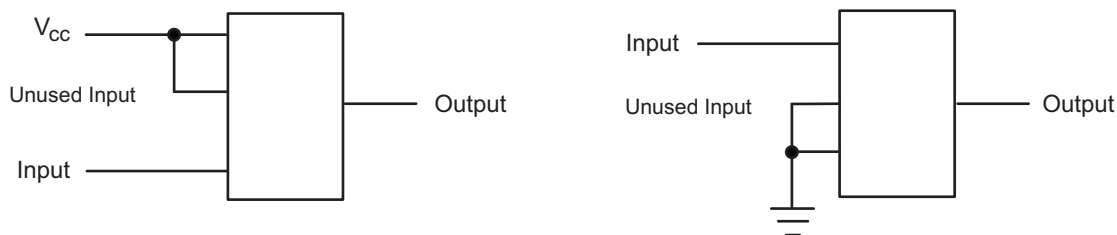


Figure 7. Layout Diagrams

13 Device and Documentation Support

13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|------------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| SN54LVC14A | Click here | Click here | Click here | Click here | Click here |
| SN74LVC14A | Click here | Click here | Click here | Click here | Click here |

13.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

13.3 Trademarks

E2E is a trademark of Texas Instruments.
 All other trademarks are the property of their respective owners.

13.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.5 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|--|-------------------------|
| 5962-9761501Q2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962- 9761501Q2A SNJ54LVC 14AFK | Samples |
| 5962-9761501QCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9761501QC A SNJ54LVC14AJ | Samples |
| 5962-9761501QDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9761501QD A SNJ54LVC14AW | Samples |
| 5962-9761501V2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962- 9761501V2A SNV54LVC 14AFK | Samples |
| 5962-9761501VCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9761501VC A SNV54LVC14AJ | Samples |
| 5962-9761501VDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9761501VD A SNV54LVC14AW | Samples |
| SN74LVC14AD | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC14A | Samples |
| SN74LVC14ADBR | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14ADBRE4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14ADE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC14A | Samples |
| SN74LVC14ADG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC14A | Samples |
| SN74LVC14ADGVR | ACTIVE | TVSOP | DGV | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14ADR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU CU SN | Level-1-260C-UNLIM | -40 to 125 | LVC14A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------------------|-------------------------|
| SN74LVC14ADRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC14A | Samples |
| SN74LVC14ADRG3 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 125 | LVC14A | Samples |
| SN74LVC14ADRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC14A | Samples |
| SN74LVC14ADT | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC14A | Samples |
| SN74LVC14ANSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LVC14A | Samples |
| SN74LVC14APW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14APWG4 | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14APWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU CU SN | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14APWRE4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14APWRG3 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14APWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14APWT | ACTIVE | TSSOP | PW | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14APWTG4 | ACTIVE | TSSOP | PW | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | LC14A | Samples |
| SN74LVC14ARGYR | ACTIVE | VQFN | RGY | 14 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | LC14A | Samples |
| SN74LVC14ARGYRG4 | ACTIVE | VQFN | RGY | 14 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 125 | LC14A | Samples |
| SNJ54LVC14AFK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962-9761501Q2A SNJ54LVC14AFK | Samples |
| SNJ54LVC14AJ | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9761501QC A SNJ54LVC14AJ | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|-----------------|-------------------------|----------------------|--------------|-------------------------------------|----------------|
| SNJ54LVC14AW | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-9761501QD A SNJ54LVC14AW | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

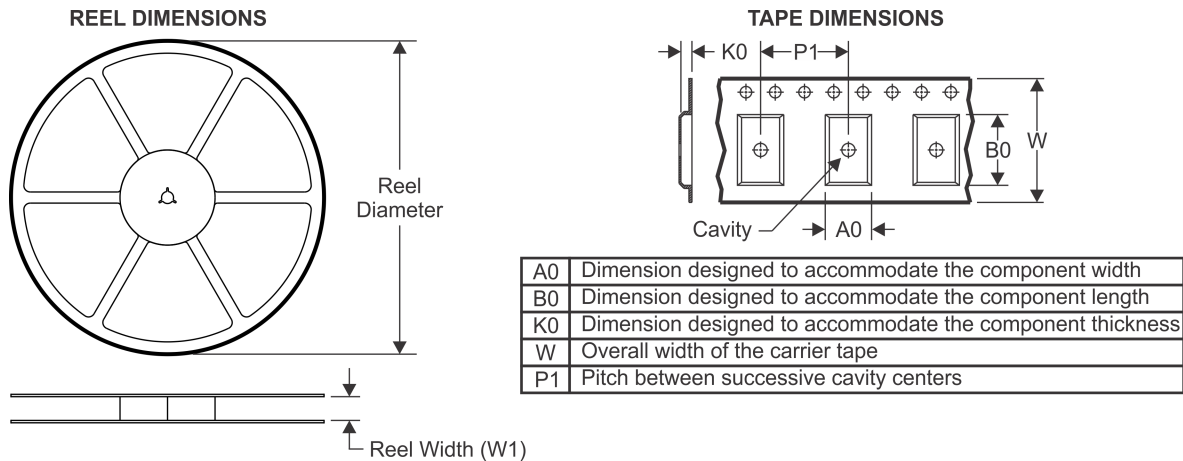
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LVC14A, SN54LVC14A-SP, SN74LVC14A :

- Catalog: [SN74LVC14A](#), [SN54LVC14A](#)
- Automotive: [SN74LVC14A-Q1](#), [SN74LVC14A-Q1](#)
- Enhanced Product: [SN74LVC14A-EP](#), [SN74LVC14A-EP](#)
- Military: [SN54LVC14A](#)
- Space: [SN54LVC14A-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVC14ADBR | SSOP | DB | 14 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LVC14ADGVR | TVSOP | DGV | 14 | 2000 | 330.0 | 12.4 | 6.8 | 4.0 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC14ADR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LVC14ADR | SOIC | D | 14 | 2500 | 330.0 | 16.8 | 6.5 | 9.5 | 2.3 | 8.0 | 16.0 | Q1 |
| SN74LVC14ADR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LVC14ADRG3 | SOIC | D | 14 | 2500 | 330.0 | 16.8 | 6.5 | 9.5 | 2.3 | 8.0 | 16.0 | Q1 |
| SN74LVC14ADRG4 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LVC14ADRG4 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LVC14ADT | SOIC | D | 14 | 250 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LVC14ANSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LVC14APWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC14APWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC14APWRG3 | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC14APWRG4 | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC14APWT | TSSOP | PW | 14 | 250 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC14ARGYR | VQFN | RGY | 14 | 3000 | 330.0 | 12.4 | 3.75 | 3.75 | 1.15 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVC14ADBR | SSOP | DB | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74LVC14ADGVR | TVSOP | DGV | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74LVC14ADR | SOIC | D | 14 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74LVC14ADR | SOIC | D | 14 | 2500 | 364.0 | 364.0 | 27.0 |
| SN74LVC14ADR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN74LVC14ADRG3 | SOIC | D | 14 | 2500 | 364.0 | 364.0 | 27.0 |
| SN74LVC14ADRG4 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN74LVC14ADRG4 | SOIC | D | 14 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74LVC14ADT | SOIC | D | 14 | 250 | 367.0 | 367.0 | 38.0 |
| SN74LVC14ANSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74LVC14APWR | TSSOP | PW | 14 | 2000 | 364.0 | 364.0 | 27.0 |
| SN74LVC14APWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74LVC14APWRG3 | TSSOP | PW | 14 | 2000 | 364.0 | 364.0 | 27.0 |
| SN74LVC14APWRG4 | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74LVC14APWT | TSSOP | PW | 14 | 250 | 367.0 | 367.0 | 35.0 |
| SN74LVC14ARGYR | VQFN | RGY | 14 | 3000 | 367.0 | 367.0 | 35.0 |

J 14

GENERIC PACKAGE VIEW
CDIP - 5.08 mm max height
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211284-2/G 08/15

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF TERMINALS ** | A | | B | |
|---------------------|------------------|------------------|------------------|------------------|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |

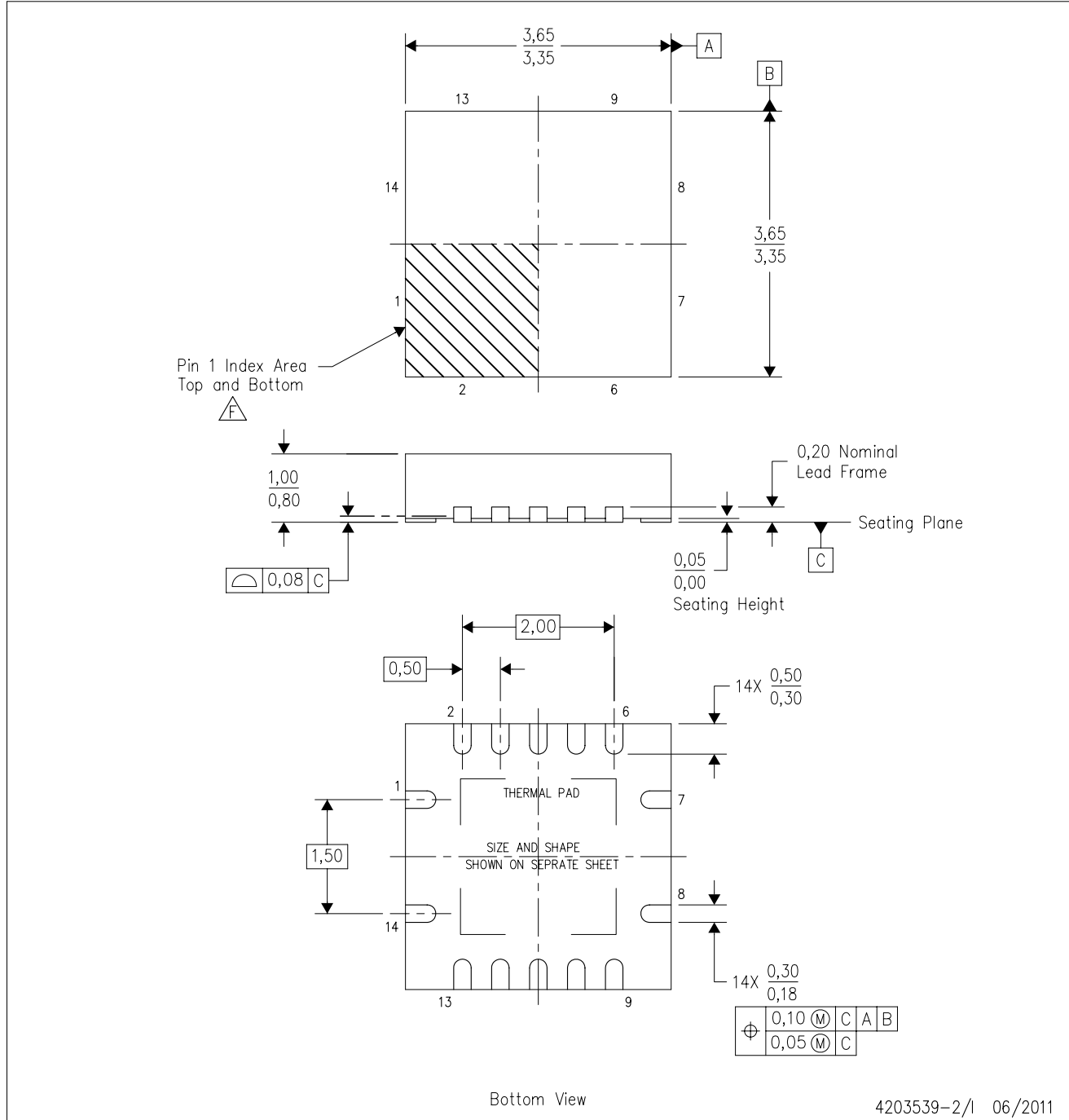



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 -  Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - G. Package complies to JEDEC MO-241 variation BA.

RGY (S-PVQFN-N14)

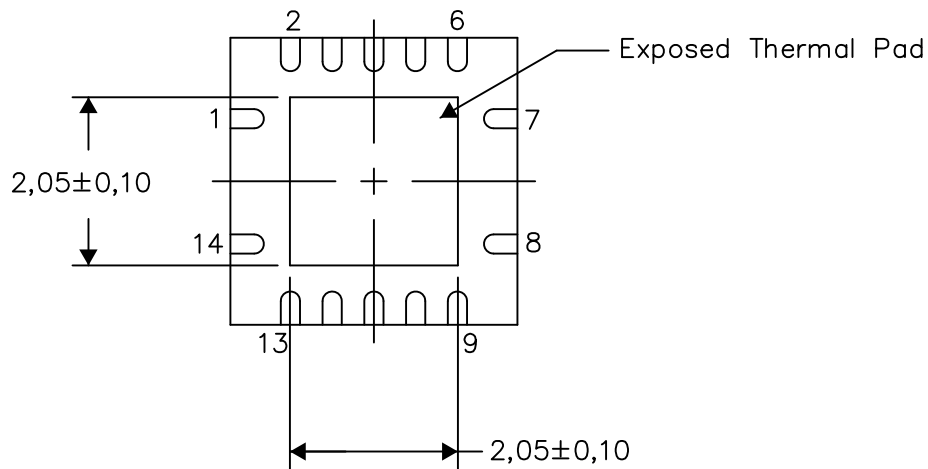
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

Exposed Thermal Pad Dimensions

4206353-2/P 03/14

NOTE: All linear dimensions are in millimeters

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



4208122-2/P 03/14

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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